

Dual N-Channel MOSFET

General Description

The WSP8810A is the highest performance trench N-ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the small power switching and load switch applications.

The WSP8810A meet the RoHS and Green Product requirement with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

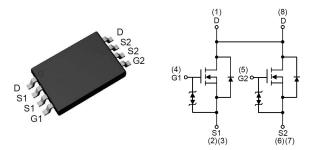
Product Summery

BVDSS	RDSON	ID
20V	14.5mΩ	7.0A

Applications

- High Frequency Point-of-Load Synchronous Small power switching for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- ESD:2KV

TSSOP-8 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units	
V _{DS}	Drain-Source Voltage	20	V	
V _{GS}	Gate-Source Voltage	±12	V	
I _D @T₀=25℃	Continuous Drain Current, $V_{GS} @ 4.5V^1$ 7.0		А	
I _D @T _c =70℃	Continuous Drain Current, V _{GS} @ 4.5V ¹	5.8	А	
I _{DM}	Pulsed Drain Current ²	20	А	
P _D @T _A =25℃	Total Power Dissipation ³	1.25	W	
T _{STG}	Storage Temperature Range -55 to 150		°C	
TJ	Operating Junction Temperature Range	-55 to 150	°C	

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit	
R _{θJA}	Thermal Resistance Junction-ambient ¹		100	°C/W	
R _{eJC}	Thermal Resistance Junction-Case ¹		70	°C/W	



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Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	20			V
$\triangle BV_{DSS} / \triangle T_J$	BVDSS Temperature Coefficient	Reference to $25^\circ\!\!\mathbb{C}$, I _D =1mA		0.022		V/℃
		V _{GS} =10V , I _D =7A		FI Ě	Œ	mΩ
		V _{GS} =4.5V , I _D =7A		FÍ	æ	
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =3.1V , I _D =5A		FÎ	G	
		V _{GS} =2.5V , I _D =4A		FΪĚ	Ĝ	
		V _{GS} =1.8V , I _D =2A		-CG	H€	
V _{GS(th)}	Gate Threshold Voltage	— V _{GS} =V _{DS} , I _D =250uA -	0.4	0.7	1.0	V
$ riangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient			-2.33		mV/℃
	Desig Ocument a studie of Ocument	V _{DS} =16V , V _{GS} =0V , T _J =25℃			1	
I _{DSS}	Drain-Source Leakage Current	V _{DS} =16V , V _{GS} =0V , T _J =55℃			uA 5	
I _{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm12V$, $V_{DS}=0V$			± 100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =5A		FH		S
R _g	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		4		Ω
Qg	Total Gate Charge (4.5V)			16	24.5	
Q _{gs}	Gate-Source Charge	V _{DS} =10V , V _{GS} =4.5V , I _D =6A		ΙÈG	0. Í	nC
Q _{gd}	Gate-Drain Charge			GÊ	7.2	
T _{d(on)}	Turn-On Delay Time			16	10	
Tr	Rise Time	V_{DD} =10V , V_{GEN} =4.5V , R_{G} =6 Ω ,		0.8	26	ns
T _{d(off)}	Turn-Off Delay Time	I _D =1A ,R∟=10Ω.		30	55	
T _f	Fall Time			5	10	
C _{iss}	Input Capacitance	V _{DS} =10V , V _{GS} =0V , f=1MHz		FGJG		
C _{oss}	Output Capacitance			FÎH		pF
Crss	Reverse Transfer Capacitance			ÌÍ		

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current ^{1,4}				2.0	А
I _{SM}	Pulsed Source Current ^{2,4}	V _G =V _D =0V , Force Current			8.0	А
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =1.5A , T _J =25℃			1.3	V
trr	Reverse Recovery Time			HF		nS
Q _{rr}	Reverse Recovery Charge	l ⊧=6A , dl/dt=100A/µs , T_J=25 ℃		ÎĚ		nC

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, t \leq 10 sec.

2.The data tested by pulsed , pulse width $\,\leq\,$ 300us , duty cycle $\,\leq\,$ 2%

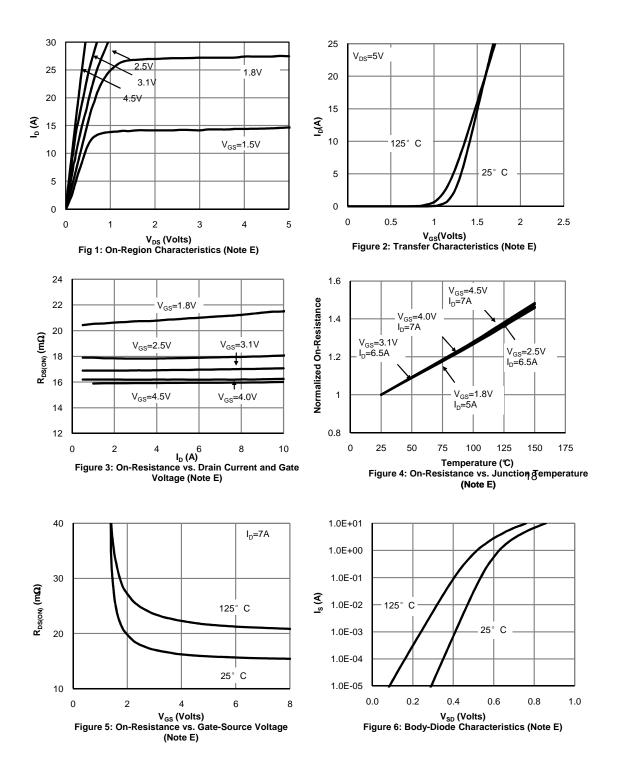
3.The power dissipation is limited by 150 $^\circ\!\!\mathbb{C}$ junction temperature

4. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



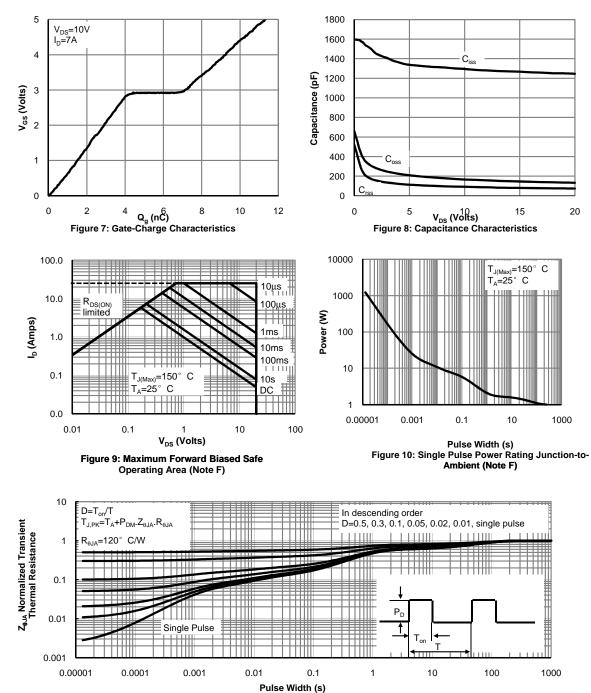
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Typical Characteristics





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Typical Characteristics

Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)



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